

Specifications

Insulation Resistance:	1,000MΩ min. at 500V DC
Dielectric Withstanding Voltage:	700V AC for 1 minute
Contact Resistance:	30mΩ max. at 10mA/20mV max.
Operating Temperature Range:	-55°C to +170°C
Contact Force:	30g min. per pin at minimum displacement of 0.45mm 90g max. per pin at maximum displacement of 0.8mm

Materials and Finish

Housing:	Polyetherimide (PEI), glass-filled
Contacts:	Beryllium Copper (BeCu)
Plating:	Gold over Nickel

Part Number (Details)

NP178 - 644 01 - x - xx

Series No.

No. of Contact Pins

Design Number

Matching IC Diameter / Socket Pin Length

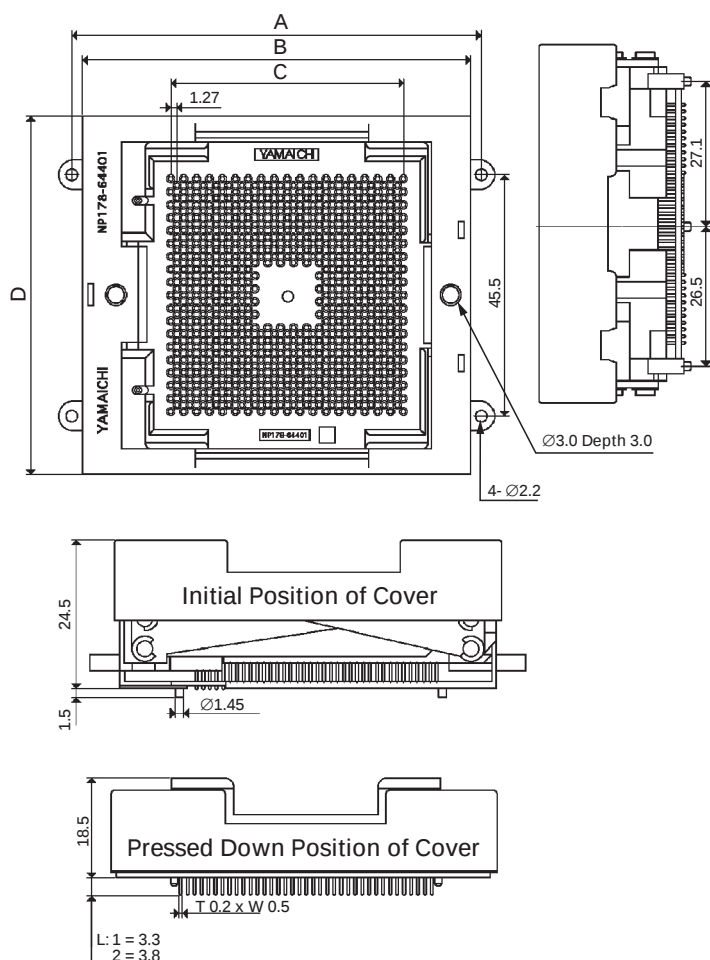
1: $\varnothing 0.35 \pm 0.05$ 1: L = 3.3
2: $\varnothing 0.45 \pm 0.05$ 2: L = 3.8

MF = Flanged

Unmarked = Not Flanged

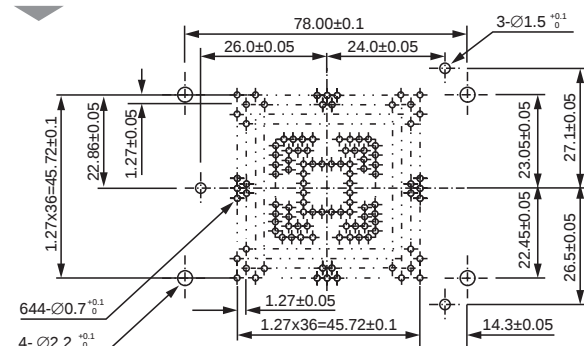
Applicable Dimensions (Reference Only)

Outline Socket Dimensions

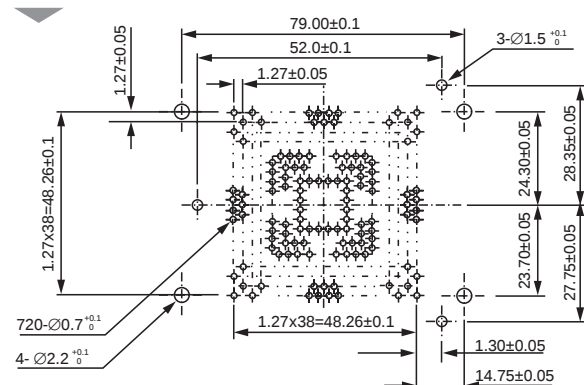


Recommended PC Board Layouts

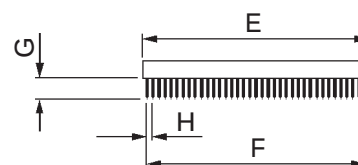
NP178-64401-x-xx



NP178-72002-x-xx



Outline IC Dimensions



Part Number	Grid Size	Pin Count	Socket Dimensions				IC Dimensions			
			A	B	C	D	E max.	F	G	H
NP178-64401-x-xx	19 x 19	644	78.0	74.0	1.27x36=45.72	67.0	□ 50.0	45.72	2.54-5.9	1.27
NP178-72002-x-xx	20 x 20	720	79.0	75.0	1.27x38=48.26	69.5	□ 52.8	48.26	2.54-5.9	1.27